ABSTRACT

A peeling apparatus 10 includes a peeling table 11 supporting a wafer W on which a sheet S is stuck and a sheet peeling unit 12 disposed above the peeling table 11, in which sheet S can be peeled off with relative movement of the sheet peeling unit 12 and the peeling table 11. The peeling apparatus 10 includes a support roll 20 of peeling tape PT, first and second rolls 30, 31 bonding the peeling tape PT to the sheet S surface, and a winding roll 21 of the peeling tape PT. Peeling-off is performed in a state of forming an initial peeling angle a1 such that a peeling tape PT is folded in an aperture C formed between the second roll 31 and the sheet S, and afterwards the sheet S is peeled off at subsequent peeling angle a2 corresponding to a diameter of the second roll 31.